

### 2.0x1.25mm BI-COLOR SMD CHIP LED LAMP



**ATTENTION** 

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES** 

Part Number: APB2012QBDCGKC

Blue Green

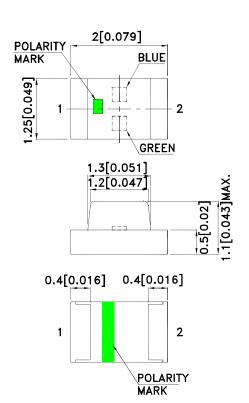
#### **Features**

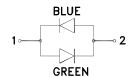
- 2.0mmx1.25mm SMT LED, 1.1mm thickness.
- Bi -color,Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

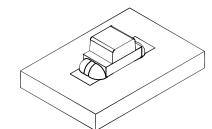
### **Descriptions**

- The Blue source color devices are made with InGaN Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- Electrostatic discharge and power surge could damage
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

## **Package Dimensions**







SPEC NO: DSAM3694

APPROVED: WYNEC

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

  4. The device has a single mounting surface. The device must be mounted according to the specifications.

**REV NO: V.3B** DATE: AUG/20/2014 PAGE: 1 OF 6 **CHECKED: Allen Liu** DRAWN: L.Q.Xie ERP: 1203013156

#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APB2012QBDCGKC	Blue (InGaN)	Water Clear	40	80	150°
	Green (AlGalnP)	Water Clear	20	50	

#### Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue Green	460 574		nm	IF=20mA
λD [1]	Dominant Wavelength	Blue Green	465 570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue Green	25 20		nm	I=20mA
С	Capacitance	Blue Green	100 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue Green	3.3 2.1	4 2.5	V	I==20mA

#### Notes:

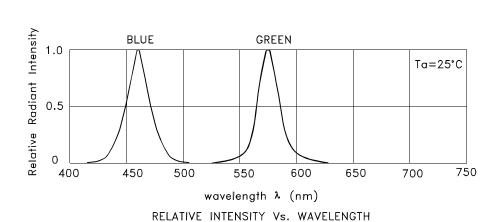
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

#### Absolute Maximum Ratings at TA=25°C

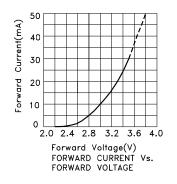
Parameter	Blue	Green	Units		
Power dissipation	120	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	150	150	mA		
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

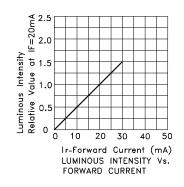
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

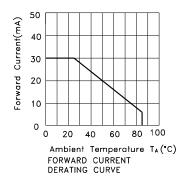
SPEC NO: DSAM3694 **REV NO: V.3B** DATE: AUG/20/2014 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: L.Q.Xie ERP: 1203013156

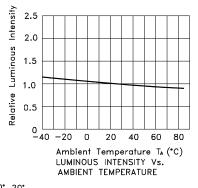


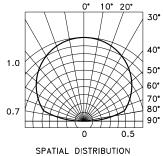
## APB2012QBDCGKC Blue





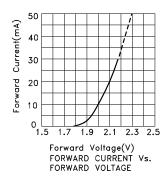


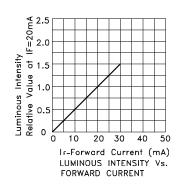


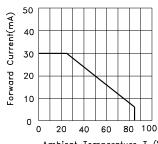


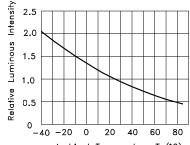
SPEC NO: DSAM3694 REV NO: V.3B DATE: AUG/20/2014 PAGE: 3 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: L.Q.Xie ERP: 1203013156

### Green



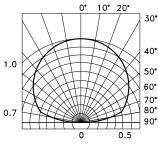












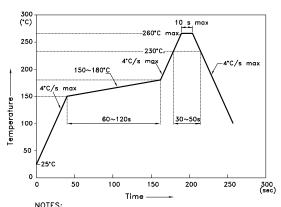
SPATIAL DISTRIBUTION

SPEC NO: DSAM3694 REV NO: V.3B DATE: AUG/20/2014 PAGE: 4 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: L.Q.Xie ERP: 1203013156

#### APB2012QBDCGKC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



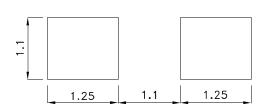
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

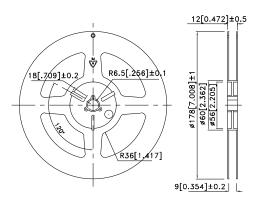
  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

  3.Number of reflow process shall be 2 times or less.

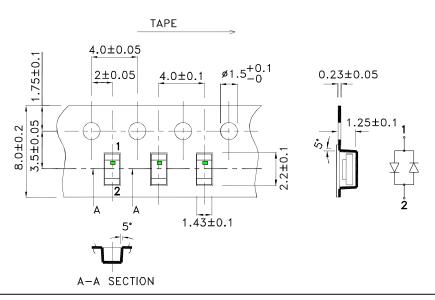
# Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



### **Reel Dimension**



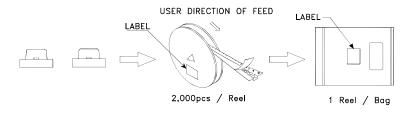
Tape Dimensions (Units : mm)

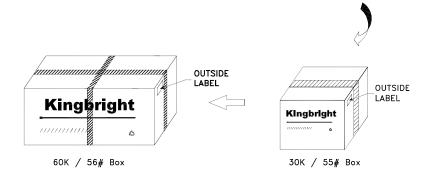


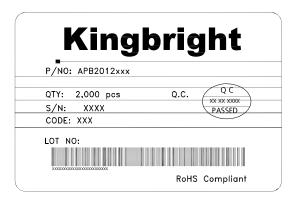
SPEC NO: DSAM3694 APPROVED: WYNEC REV NO: V.3B CHECKED: Allen Liu DATE: AUG/20/2014 DRAWN: L.Q.Xie PAGE: 5 OF 6 ERP: 1203013156

#### **PACKING & LABEL SPECIFICATIONS**

#### APB2012QBDCGKC







### Terms and conditions for the usage of this document

- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2.The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- 5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- 6.All design applications should refer to Kingbright application notes available at <a href="http://www.KingbrightUSA.com/ApplicationNotes">http://www.KingbrightUSA.com/ApplicationNotes</a>

SPEC NO: DSAM3694 REV NO: V.3B DATE: AUG/20/2014 PAGE: 6 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: L.Q.Xie ERP: 1203013156